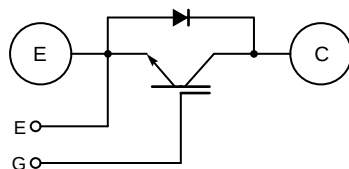
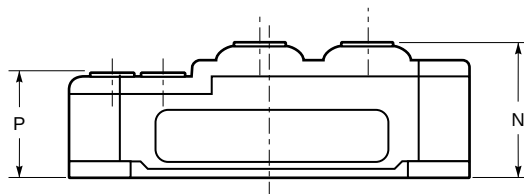
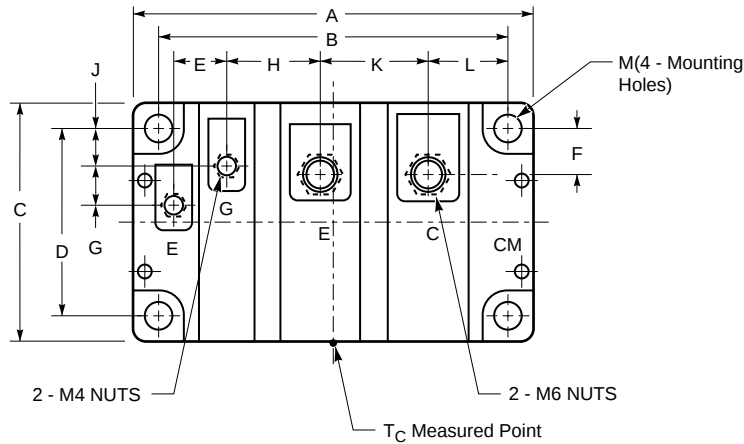


MITSUBISHI IGBT MODULES
CM400HU-24H
 HIGH POWER SWITCHING USE
 INSULATED TYPE



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.21	107.0
B	3.66±0.01	93.0±0.25
C	2.44	62.0
D	1.89±0.01	48.0±0.25
E	0.53	13.5
F	0.37	9.5
G	0.45	11.5

Dimensions	Inches	Millimeters
H	0.96	24.5
J	0.31	8.0
K	1.14	29.0
L	0.81	20.5
M	0.26 Dia.	6.5 Dia.
N	1.34 +0.04/-0.02	34 +1.0/-0.5
P	1.02 +0.04/-0.02	26 +1.0/-0.5



Description:

Mitsubishi IGBT Modules are designed for use in switching applications. Each module consists of one IGBT in a single configuration with a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- u Low Drive Power
- u Low $V_{CE(sat)}$
- u Discrete Super-Fast Recovery Free-Wheel Diode
- u High Frequency Operation
- u Isolated Baseplate for Easy Heat Sinking

Applications:

- u AC Motor Control
- u Motion/Servo Control
- u UPS
- u Welding Power Supplies

Ordering Information:

Example: Select the complete module number you desire from the table - i.e. CM400HU-24H is a 1200V (V_{CES}), 400 Ampere Single IGBT Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	400	24

CM400HU-24H

HIGH POWER SWITCHING USE
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Ratings	Symbol	CM400HU-24H	Units
Junction Temperature	T_j	-40 to 150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage (G-E SHORT)	V_{CES}	1200	Volts
Gate-Emitter Voltage (C-E SHORT)	V_{GES}	± 20	Volts
Collector Current ($T_c = 25^\circ\text{C}$)	I_C	400	Amperes
Peak Collector Current ($T_j \leq 150^\circ\text{C}$)	I_{CM}	800*	Amperes
Emitter Current** ($T_c = 25^\circ\text{C}$)	I_E	400	Amperes
Peak Emitter Current**	I_{EM}	800*	Amperes
Maximum Collector Dissipation ($T_c = 25^\circ\text{C}$)	P_C	2100	Watts
Mounting Torque, M6 Main Terminal, M6 Mounting	—	3.5~4.5	N · m
Mounting Torque, M4 Terminal	—	1.3~1.7	N · m
Weight	—	450	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	V_{iso}	2500	Vrms

* Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed $T_{j(max)}$ rating.

**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

Static Electrical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I_{CES}	$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	2	mA
Gate Leakage Voltage	I_{GES}	$V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	0.5	μA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 40\text{mA}, V_{CE} = 10V$	4.5	6	7.5	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 400A, V_{GE} = 15V, T_j = 25^\circ\text{C}$	—	2.9	3.7	Volts
		$I_C = 400A, V_{GE} = 15V, T_j = 125^\circ\text{C}$	—	2.85	—	Volts
Total Gate Charge	Q_G	$V_{CC} = 600V, I_C = 400A, V_{GE} = 15V$	—	1500	—	nC
Emitter-Collector Voltage*	V_{EC}	$I_E = 400A, V_{GE} = 0V$	—	—	3.2	Volts

* Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed $T_{j(max)}$ rating.Dynamic Electrical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics		Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance		C _{ies}	V _{CE} = 10V, V _{GE} = 0V	—	—	60	nF
Output Capacitance		C _{oes}		—	—	21	nF
Reverse Transfer Capacitance		C _{res}		—	—	12	nF
Resistive Load	Turn-on Delay Time	t _{d(on)}	V _{CC} = 600V, I _C = 400A,	—	—	250	ns
	Rise Time	t _r	V _{GE1} = V _{GE2} = 15V,	—	—	350	ns
Switch	Turn-off Delay Time	t _{d(off)}	R _G = 0.78Ω, Resistive	—	—	350	ns
Times	Fall Time	t _f	Load Switching Operation	—	—	350	ns
Diode Reverse Recovery Time		t _{rr}	I _E = 400A, di _E /dt = -800A/μs	—	—	300	ns
Diode Reverse Recovery Charge		Q _{rr}	I _E = 400A, di _E /dt = -800A/μs	—	2.2	—	μC

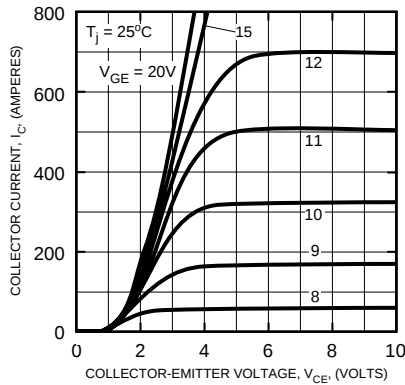
Thermal and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)Q}$	Per IGBT Module	—	—	0.06	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{th(j-c)D}$	Per FWDi Module	—	—	0.09	$^\circ\text{C/W}$
Contact Thermal Resistance	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	—	0.02	—	$^\circ\text{C/W}$

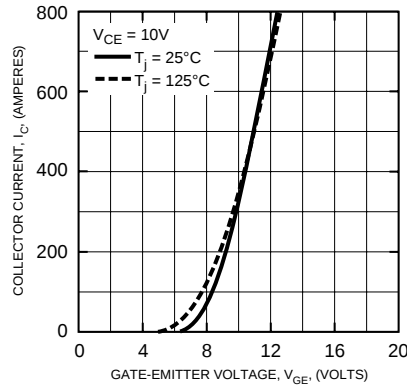
CM400HU-24H

HIGH POWER SWITCHING USE
INSULATED TYPE

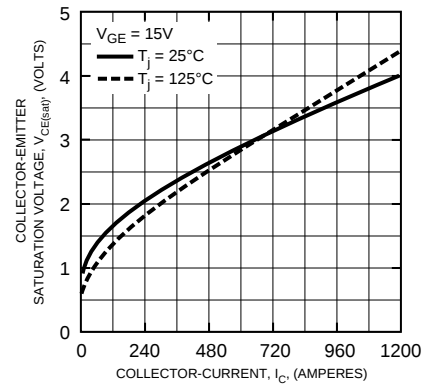
OUTPUT CHARACTERISTICS
(TYPICAL)



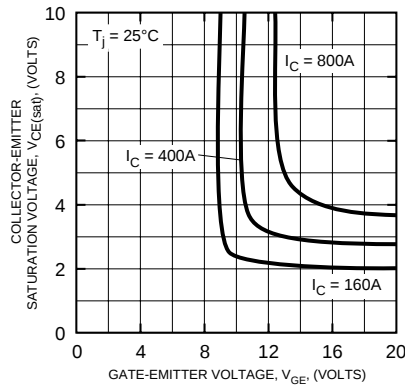
TRANSFER CHARACTERISTICS
(TYPICAL)



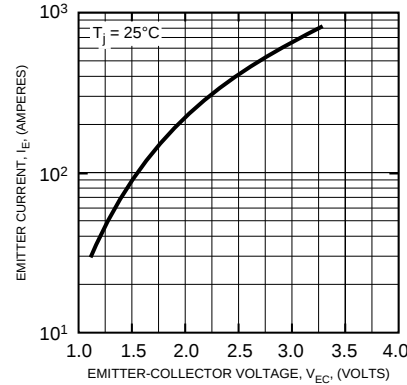
COLLECTOR-EMITTER
SATURATION VOLTAGE CHARACTERISTICS
(TYPICAL)



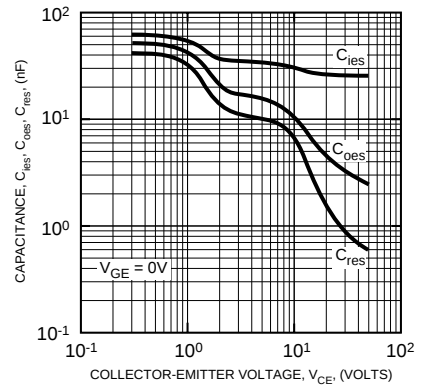
COLLECTOR-EMITTER
SATURATION VOLTAGE CHARACTERISTICS
(TYPICAL)



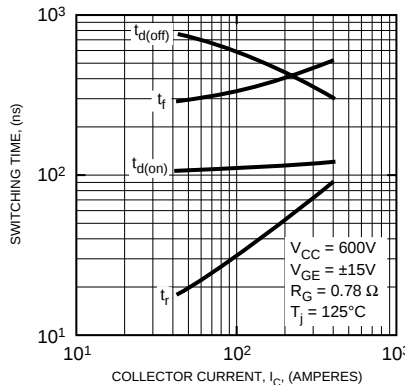
FREE-WHEEL DIODE
FORWARD CHARACTERISTICS
(TYPICAL)



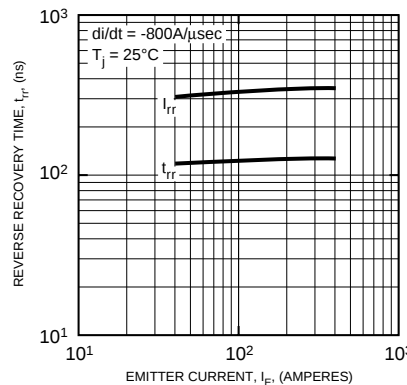
CAPACITANCE VS. V_{CE}
(TYPICAL)



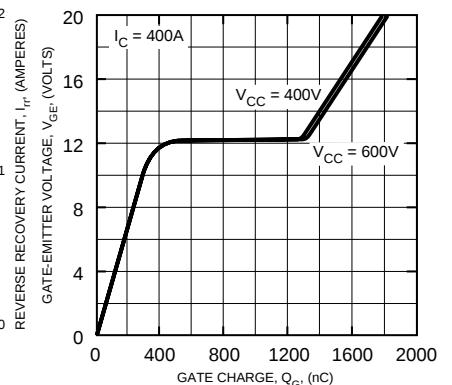
HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)



REVERSE RECOVERY CHARACTERISTICS
(TYPICAL)



GATE CHARGE, V_{GE}



CM400HU-24H

HIGH POWER SWITCHING USE
INSULATED TYPE

